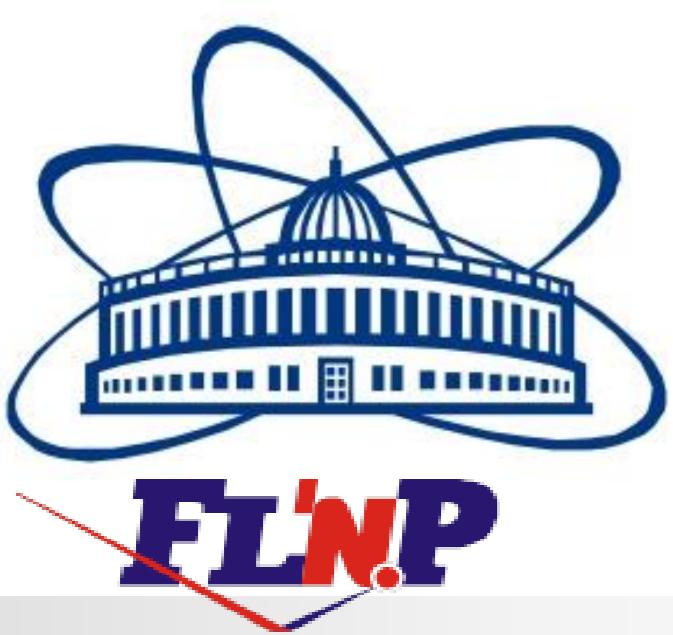


Effect of ion irradiation of solid surfaces and multilayer structures for the formation of the transition regions at the borders of semiconductor dielectric and the definition of their properties: optical, chemical composition and atoms

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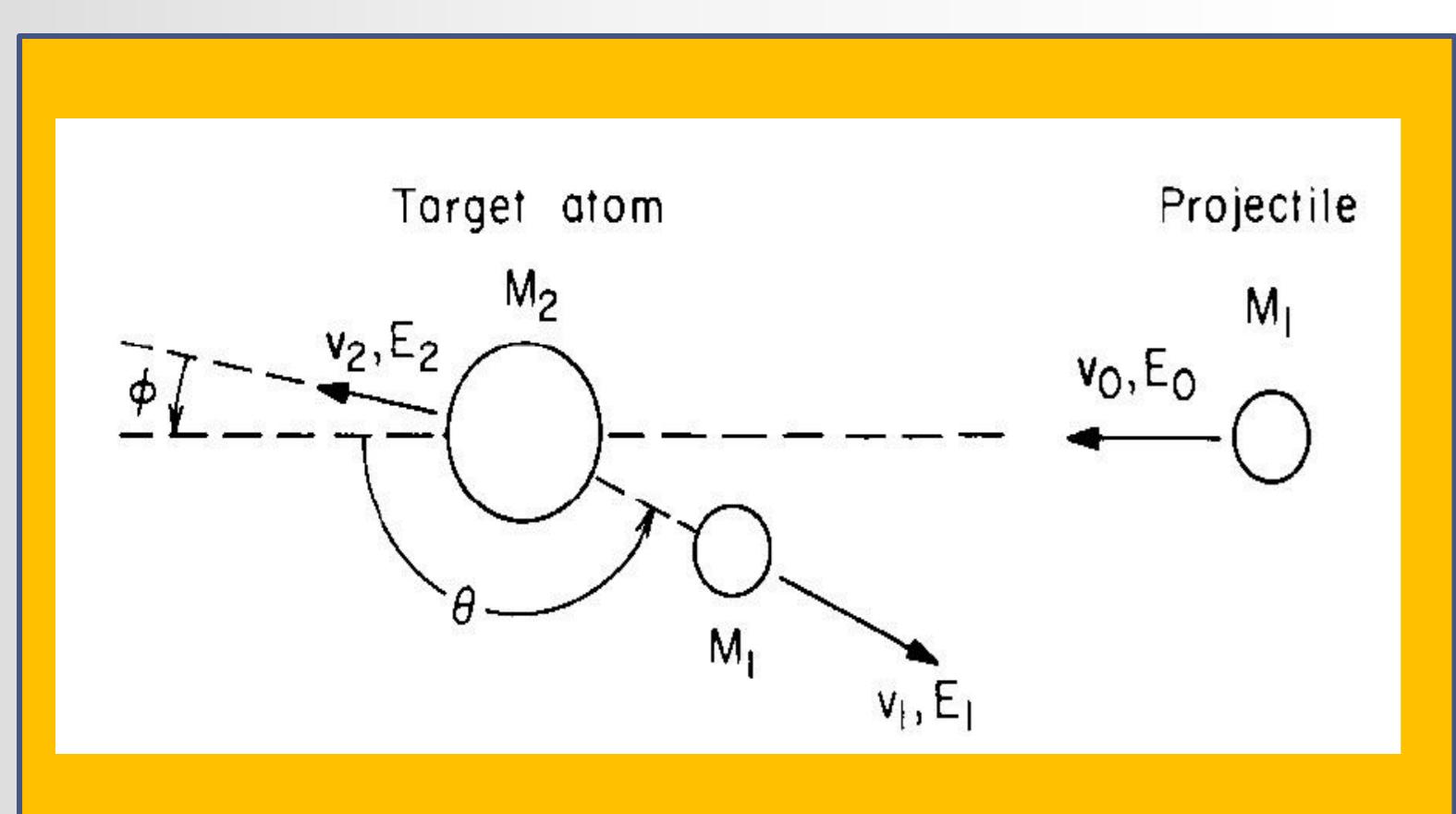
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Multilayer systems and semiconductors

RBS - exp

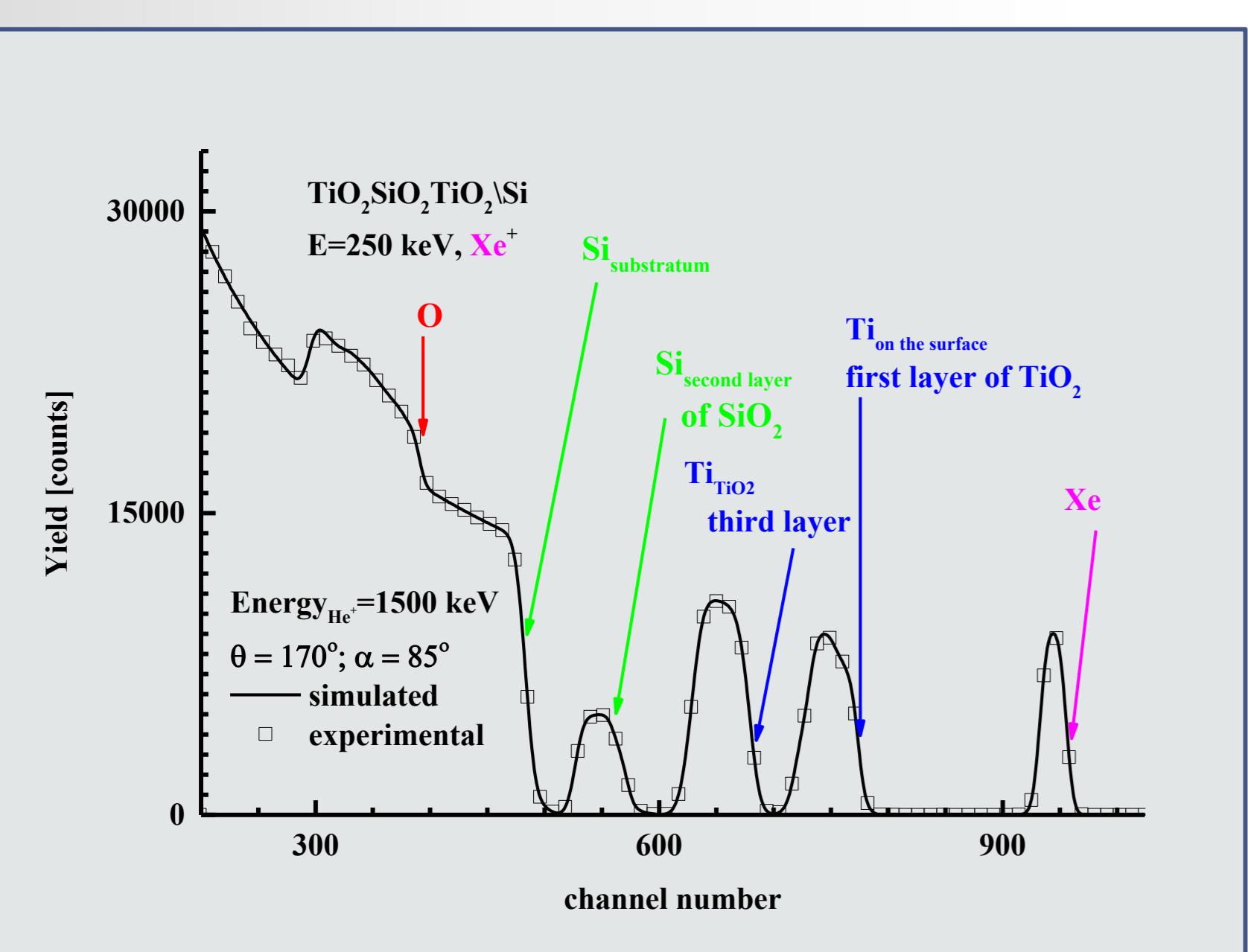
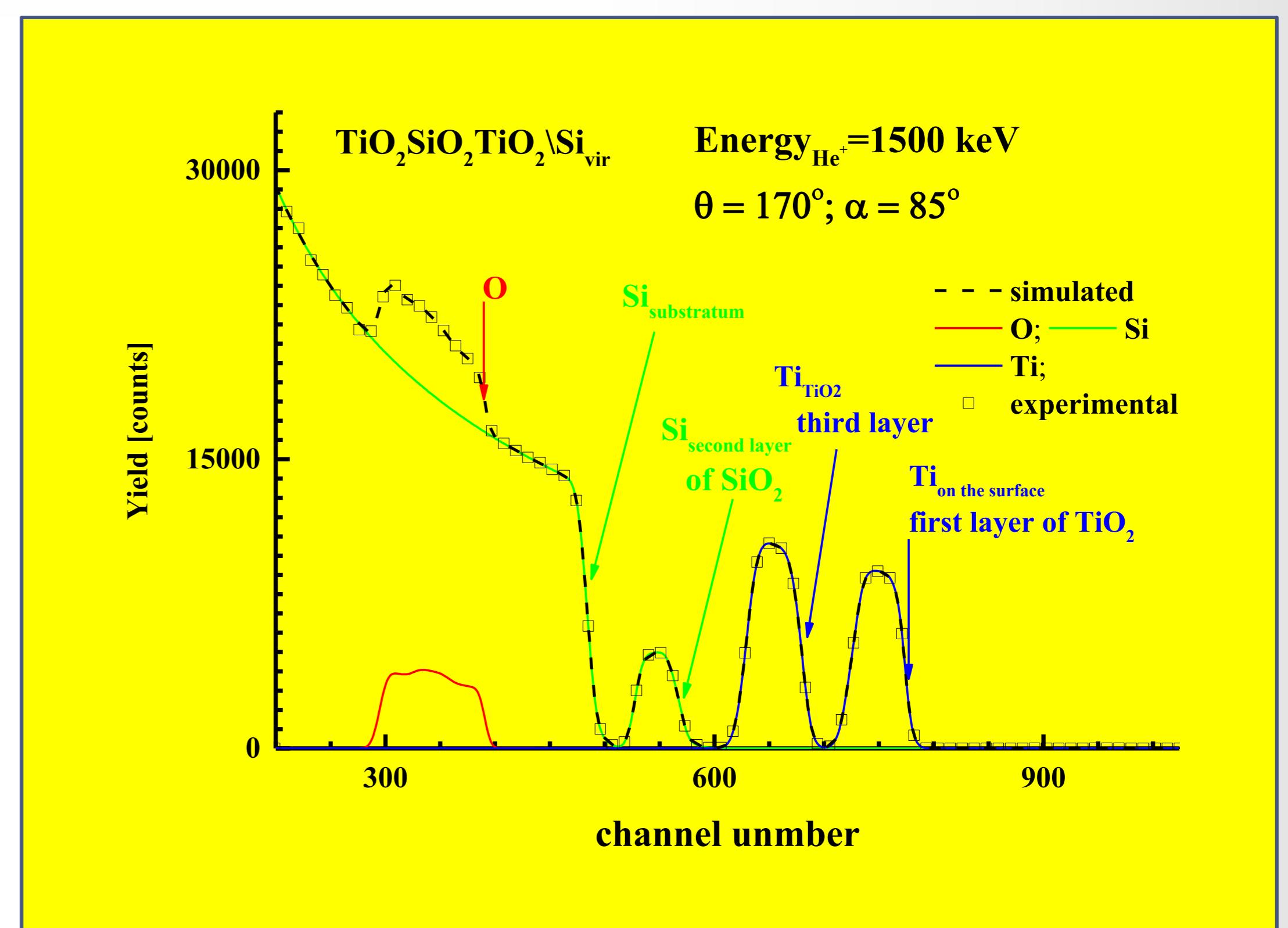


$$\frac{1}{2}M_1 v_0^2 = \frac{1}{2}M_1 v_1^2 + \frac{1}{2}M_2 v_2^2,$$

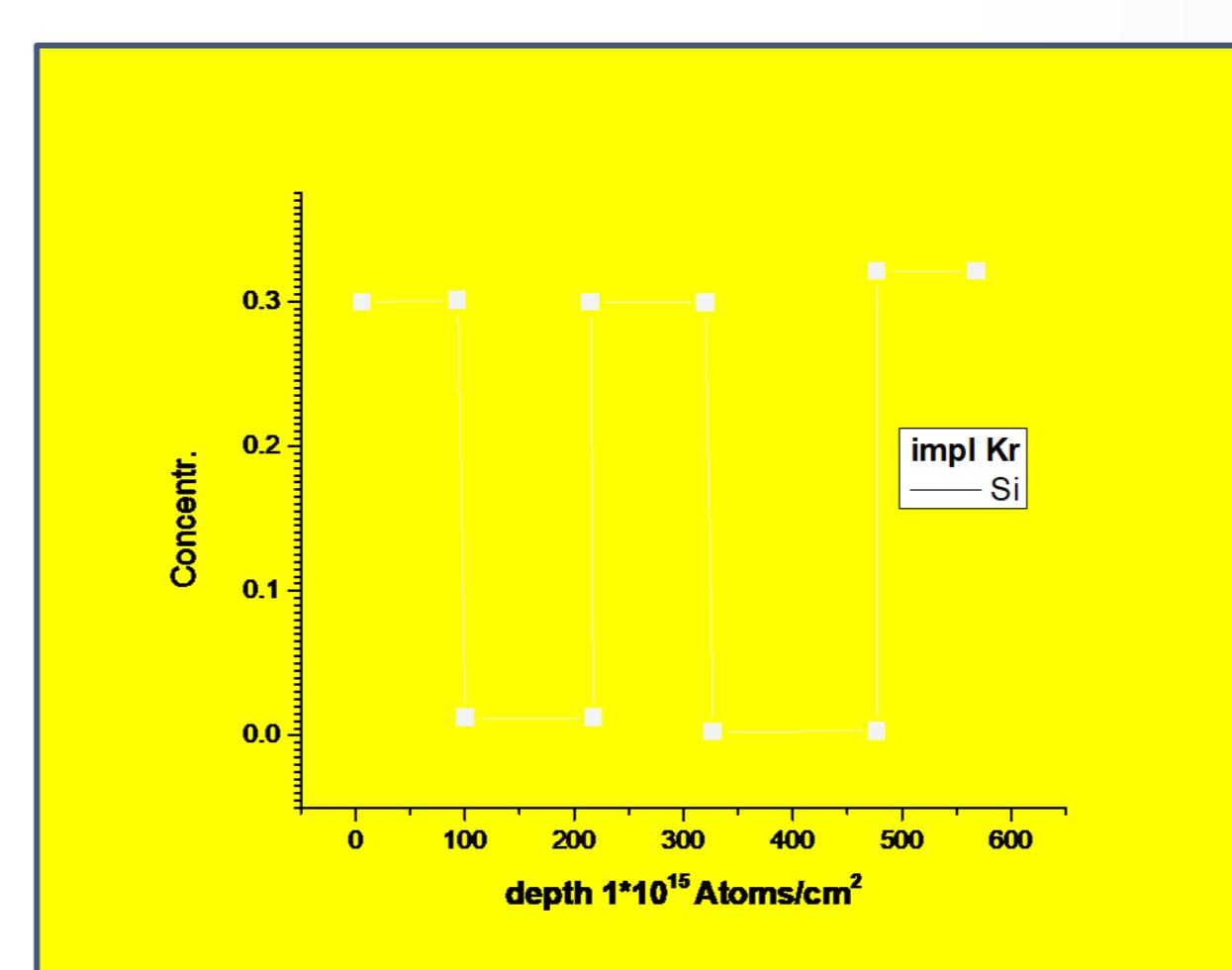
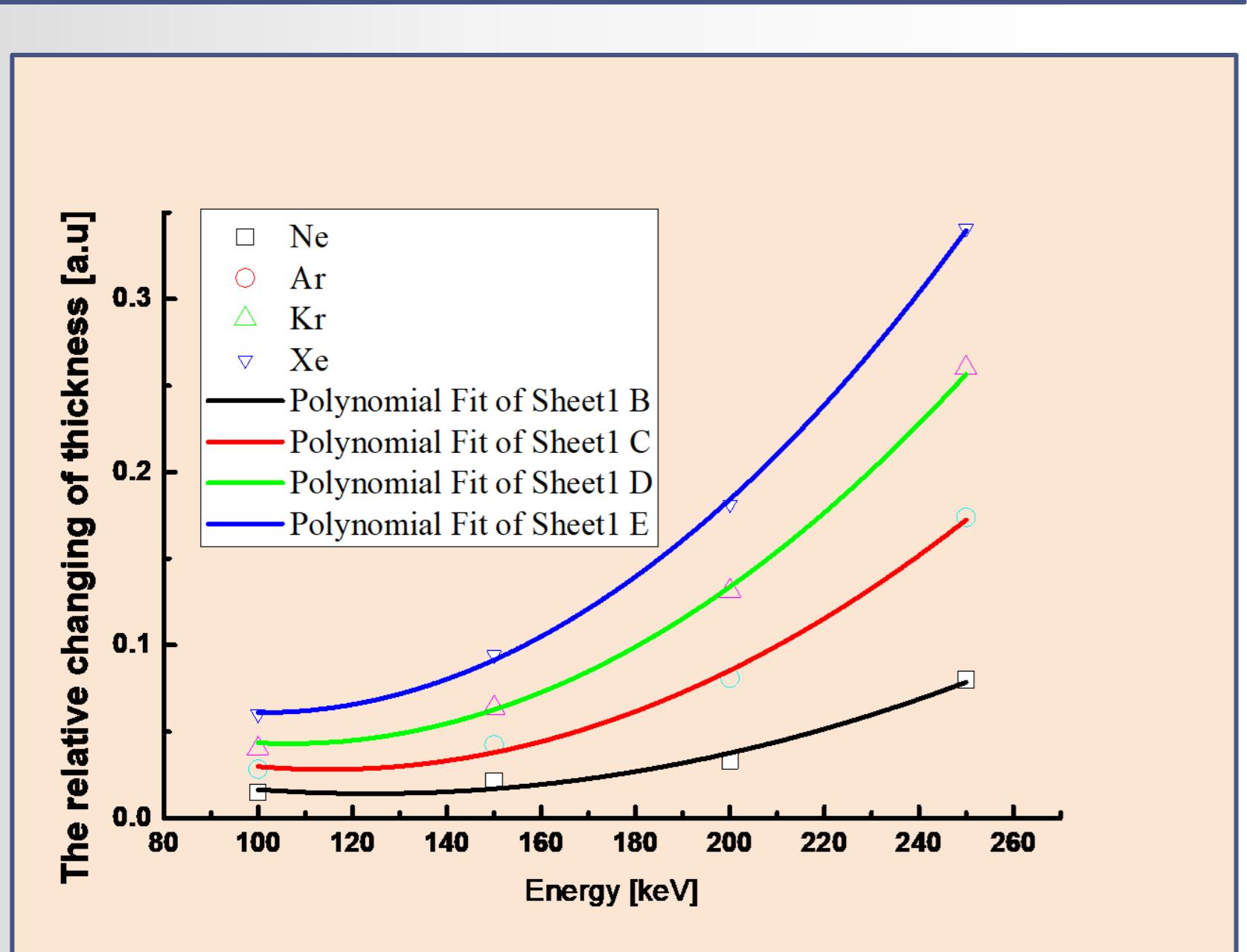
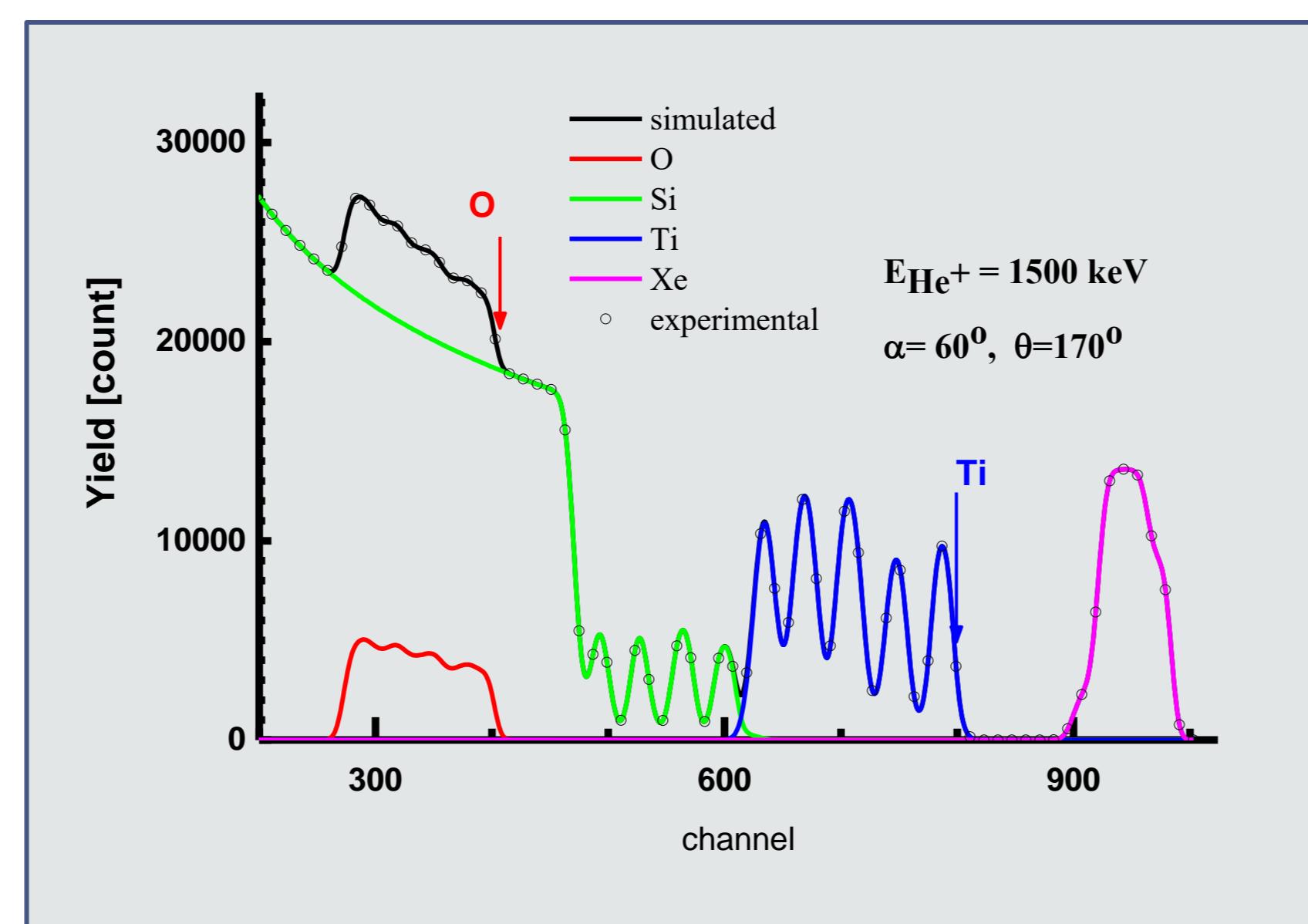
$$M_1 v_0 = M_1 v_1 \cos \theta + M_2 v_2 \cos \phi,$$

$$0 = M_1 v_1 \sin \theta - M_2 v_2 \sin \phi.$$

Before ion impl.



Before Ion Impl.			
thickness layer [1x10 ¹⁵ atom/cm ²]	Si	O	Ti
95	0.33	0.67	0.00
105	0.00	0.33	0.67
114	0.33	0.67	0.00
175	0.00	0.33	0.67
115	0.33	0.67	



It is noted that at the interface between TiO_2 and Si layers, a transitional layer is formed in the process of ion implication. This is related to the displacement of the Ti and O atoms.

